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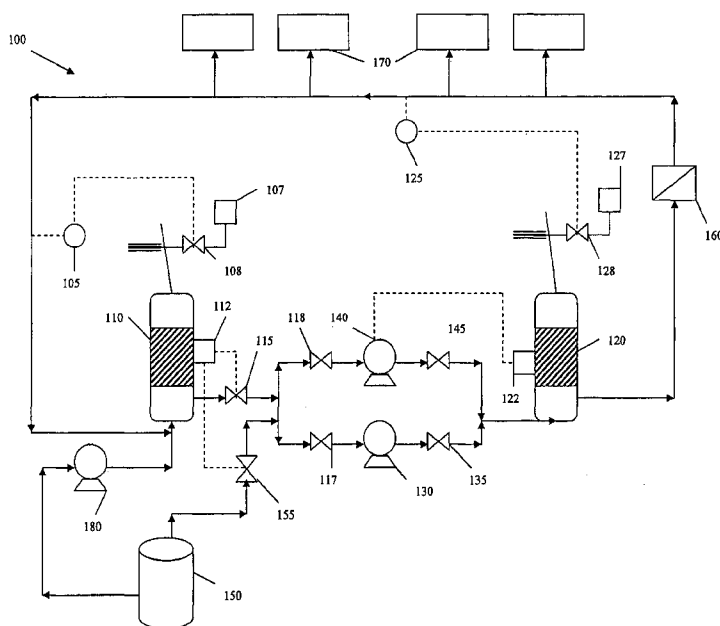
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(54) Title: LIQUID DISPENSE SYSTEM



(57) Abstract: The present invention provides a system, apparatus and method for supplying liquid through a dispensing loop to tools requiring such liquid. In particular, the present invention provides a system, apparatus and method for supplying liquid or slurry to CMP (chemical mechanical polishing) tools of a semiconductor manufacturing process. In accordance with the present invention, the liquid is delivered at a consistent flow rate and pressure to the tools, by controlling the flow rate and pressure through the use of pumps combined with flow or pressure sensors in the dispense loop.

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